

**N - CHANNEL ENHANCEMENT MODE
POWER MOS TRANSISTORS**

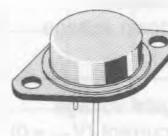
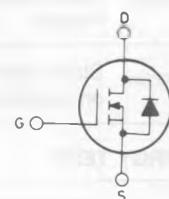
TYPE	V _{DSS}	R _{DS(on)}	I _D
SGSP591	60 V	0.033 Ω	40 A
SGSP592	50 V	0.033 Ω	40 A

- HIGH SPEED SWITCHING APPLICATIONS
- 50 - 60 VOLTS FOR INVERTERS AND UPS
- HIGH CURRENT - V_{DS(on)} ≤ 1V at 20A
- RATED FOR UNCLAMPED INDUCTIVE SWITCHING (ENERGY TEST) ♦
- EASY DRIVE - REDUCES SIZE AND COST

INDUSTRIAL APPLICATIONS:

- DC/DC CONVERTERS
- MOTOR CONTROLS

N - channel enhancement mode POWER MOS field effect transistors. Easy drive and very fast switching times make these POWER MOS transistors ideal for high speed switching circuits applications such as DC/DC converters, UPS, inverters, battery chargers and solar power converters.


TO-3
**INTERNAL SCHEMATIC
DIAGRAM**

ABSOLUTE MAXIMUM RATINGS

		SGSP591	SGSP592	
V _{DS}	Drain-source voltage (V _{GS} = 0)	60	50	V
V _{DGR}	Drain-gate voltage (R _{GS} = 20 KΩ)	60	50	V
V _{GS}	Gate-source voltage		±20	V
I _D	Drain current (cont.) at T _c = 25°C	40		A
I _D	Drain current (cont.) at T _c = 100°C	25		A
I _{DM} (*)	Drain current (pulsed)	160		A
P _{tot}	Total dissipation at T _c < 25°C	150		W
	Derating factor	1.2		W/°C
T _{stg}	Storage temperature		- 65 to 150	°C
T _j	Max. operating junction temperature		150	°C

(*) Pulse width limited by safe operating area

♦ Introduced in 1988 week 44

THERMAL DATA

$R_{thj \cdot case}$	Thermal resistance junction-case	max	0.83	$^{\circ}C/W$
T_L	Maximum lead temperature for soldering purpose		275	$^{\circ}C$

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise specified)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
------------	-----------------	------	------	------	------

OFF

$V_{(BR) DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu A$ for SGSP591 for SGSP592	$V_{GS} = 0$	60			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating} \times 0.8$	$T_c = 125^{\circ}C$		250	1000	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20 V$			± 100	nA	

ON (*)

$V_{GS \text{ (th)}}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu A$	2		4	V
$R_{DS \text{ (on)}}$	Static drain-source on resistance	$V_{GS} = 10 V$ $V_{GS} = 10 V$	$I_D = 20 A$ $I_D = 20 A$		$T_c = 100^{\circ}C$	33 66	$m\Omega$ $m\Omega$

ENERGY TEST

I_{UIS}	Unclamped inductive switching current (single pulse)	$V_{DD} = 30 V$ starting $T_j = 25^{\circ}C$	$L = 100 \mu H$	40			A
-----------	--	---	-----------------	----	--	--	---

DYNAMIC

g_{fs}	Forward transconductance	$V_{DS} = 25 V$	$I_D = 20 A$	10			mho
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 V$ $V_{GS} = 0$	$f = 1 MHz$		1900	2800 1500 850	pF pF pF

SWITCHING

$t_d \text{ (on)}$ t_r $t_d \text{ (off)}$ t_f	Turn-on time Rise time Turn-off delay time Fall time	$V_{DD} = 25 V$ $V_i = 10 V$ (see test circuit)	$I_D = 20 A$ $R_i = 4.7 \Omega$	35 110 90 55	45 145 120 70	ns ns ns ns
---	---	---	------------------------------------	-----------------------	------------------------	----------------------

ELECTRICAL CHARACTERISTICS (Continued)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
------------	-----------------	------	------	------	------

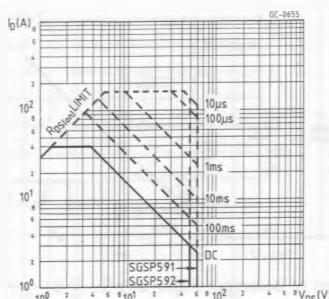
SOURCE DRAIN DIODE

I _{SD}	Source-drain current			40	A
I _{SDM} (*)	Source-drain current (pulsed)			160	A
V _{SD}	Forward on voltage	I _{SD} = 40 A	V _{GS} = 0	1.4	V
t _{rr}	Reverse recovery time	I _{SD} = 40 A di/dt = 25 A/μs	V _{GS} = 0	140	ns

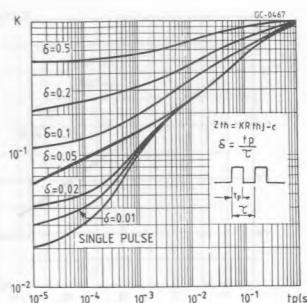
(*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5%

(*) Pulse width limited by safe operating area

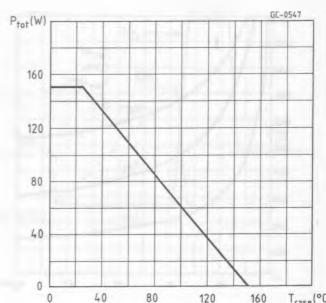
Safe operating areas



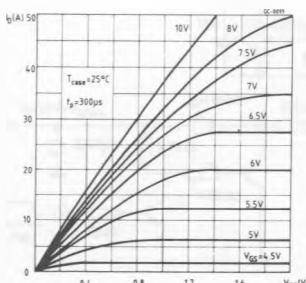
Thermal impedance



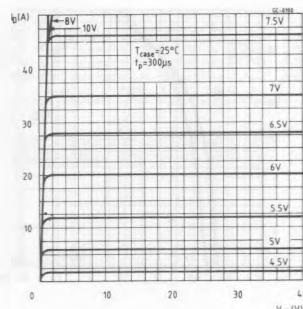
Derating curve



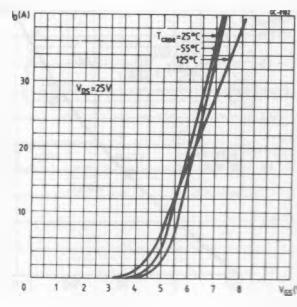
Output characteristics



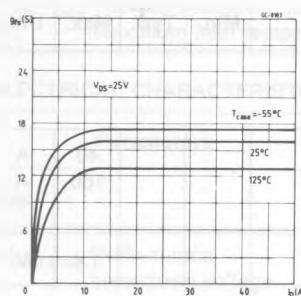
Output characteristics



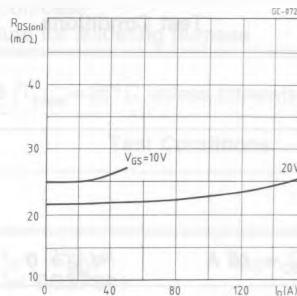
Transfer characteristics



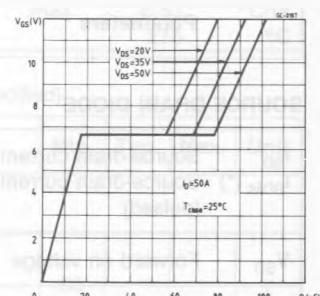
Transconductance



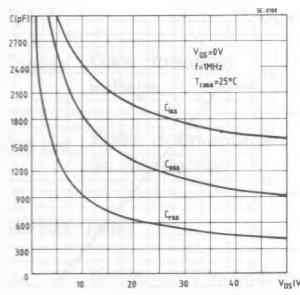
Static drain-source on resistance



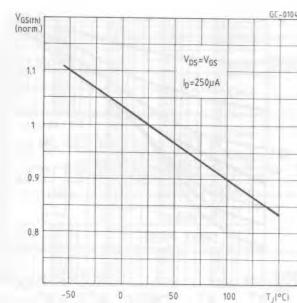
Gate charge vs gate-source voltage



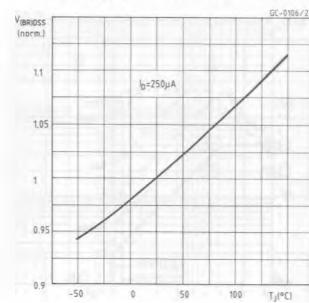
Capacitance variation



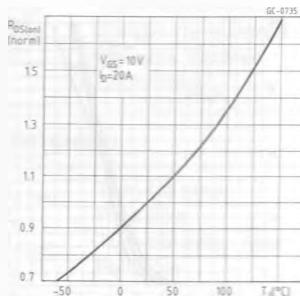
Normalized gate threshold voltage vs temperature



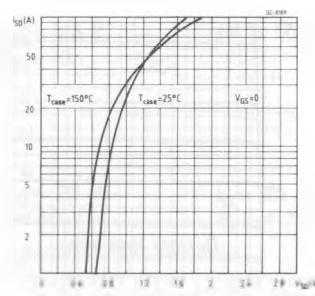
Normalized breakdown voltage vs temperature



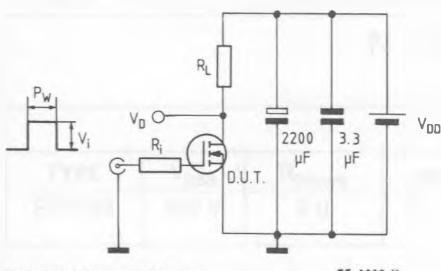
Normalized on resistance vs temperature



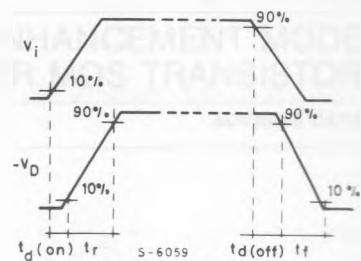
Source-drain diode forward characteristics



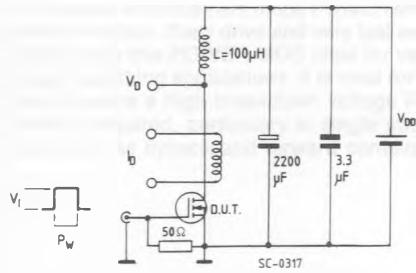
Switching times test circuit for resistive load



Switching time waveforms for resistive load

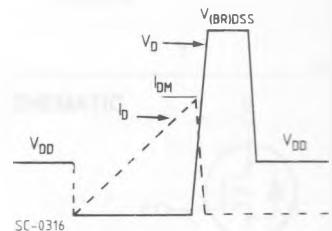


Unclamped inductive load test circuit

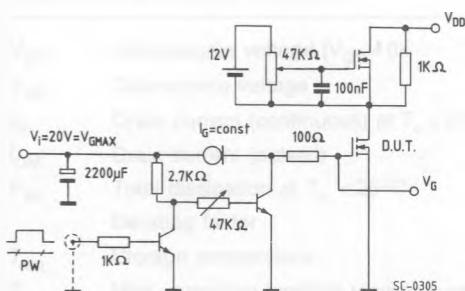


$V_i = 12 \text{ V}$ - Pulse width: adjusted to obtain specified I_{DM}

Unclamped inductive waveforms



Gate charge test circuit



PW adjusted to obtain required V_G

Body-drain diode t_{rr} measurement
Jedec test circuit